



Click [here](#) for the 3D model.

General Information

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|--------------------------|---|
| Series | KONNEKT Auto COG |
| Style | KONNEKT |
| Description | SMD, MLCC, KONNEKT, Ultra-Stable, Class I |
| Features | High Density Packaging |
| RoHS | Yes |
| Termination | Tin |
| Qualifications | AEC-Q200 |
| AEC-Q200 | Yes |
| Typical Component Weight | 190 mg |
| Chip Size | 1812-2 |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

| | |
|--|---------------------|
| Capacitance | 0.44 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 10% |
| Voltage DC | 50 VDC |
| Dielectric Withstanding Voltage | 125 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 PPM/C |
| Dissipation Factor | 0.1% 1 kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 1.136 GOhms |

Dimensions

| | |
|---|-----------------|
| L | 4.5mm +/-0.3mm |
| W | 3.2mm +/-0.3mm |
| T | 3.3mm +/-0.4mm |
| B | 0.6mm +/-0.35mm |

Packaging Specifications

| | |
|--------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 500 |

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